

Supporting Information for

Hybrid NiO-CuO mesoporous nanowires array with abundant oxygen vacancies and hollow structure for high-performance asymmetric supercapacitor

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Fig. S21. (a) TEM and (b) HR-TEM images of the NiO-CuO with Ni:Cu = 1:1 after 5 000 charge/discharge cycles.

Table S1. Previously reported data on metal oxides based electrodes in comparison with our work result.

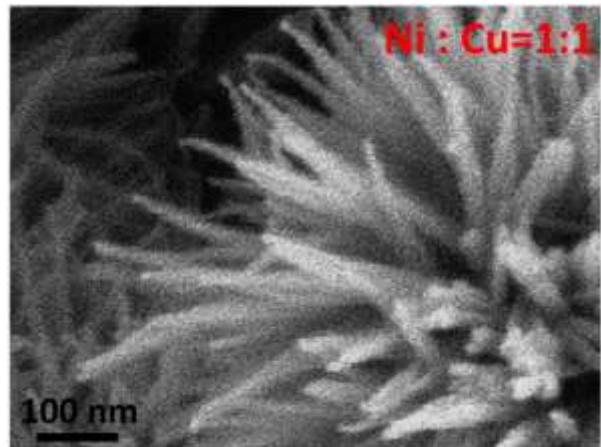


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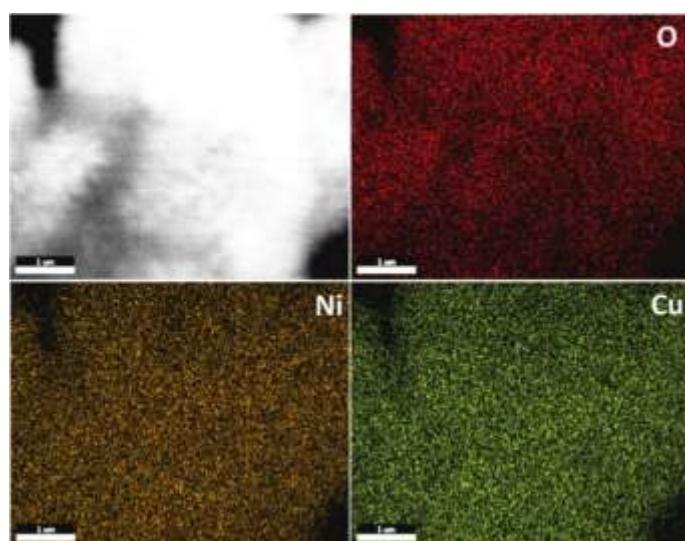


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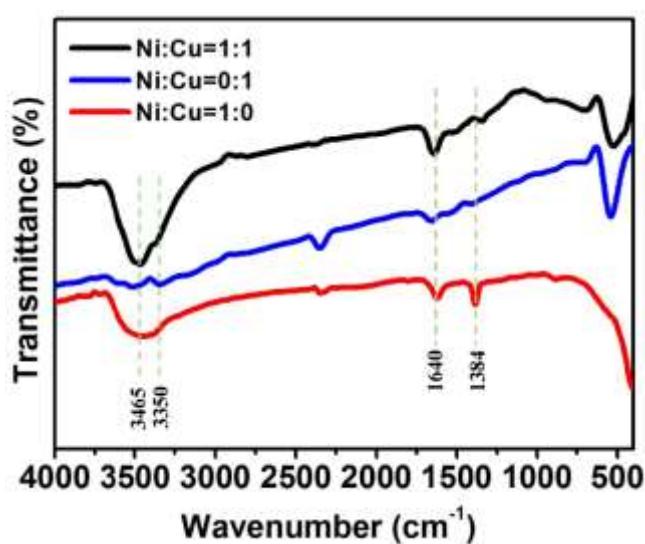


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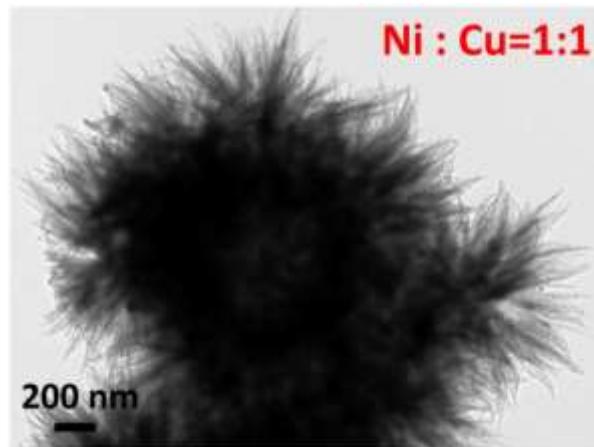


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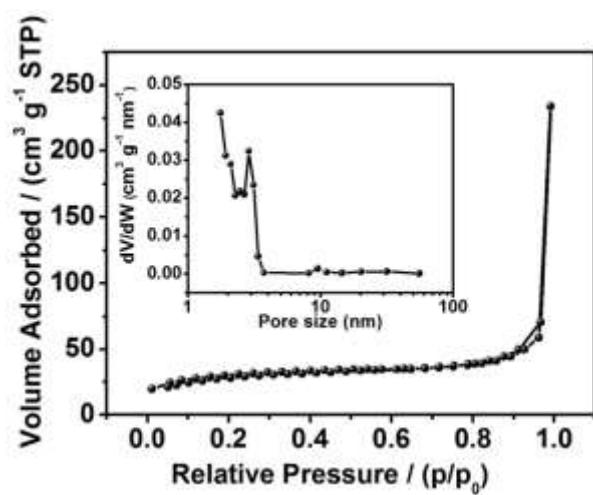


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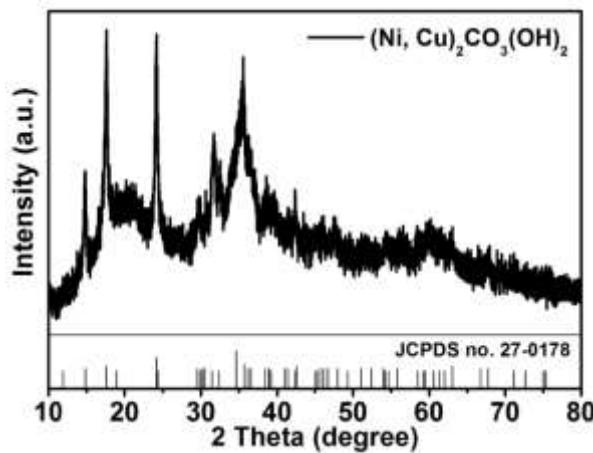


Fig. S6. XRD pattern of the hydrothermal product $(\text{Ni}, \text{Cu})_2\text{CO}_3(\text{OH})_2$ before annealing.

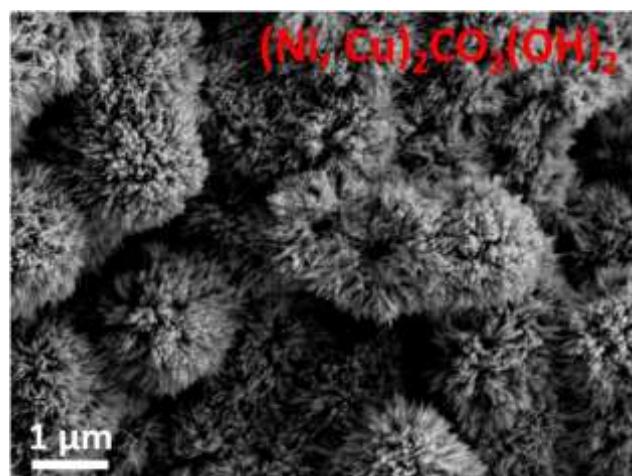


Fig. S7. SEM image of the hydrothermal product $(\text{Ni}, \text{Cu})_2\text{CO}_3(\text{OH})_2$ before annealing.

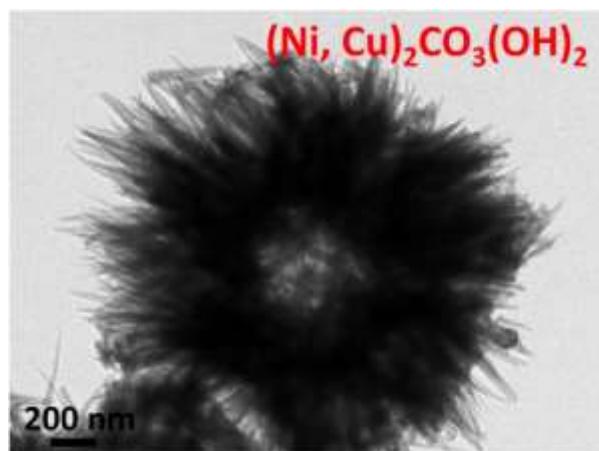


Fig. S8. TEM image of the hydrothermal product $(\text{Ni}, \text{Cu})_2\text{CO}_3(\text{OH})_2$ before annealing.

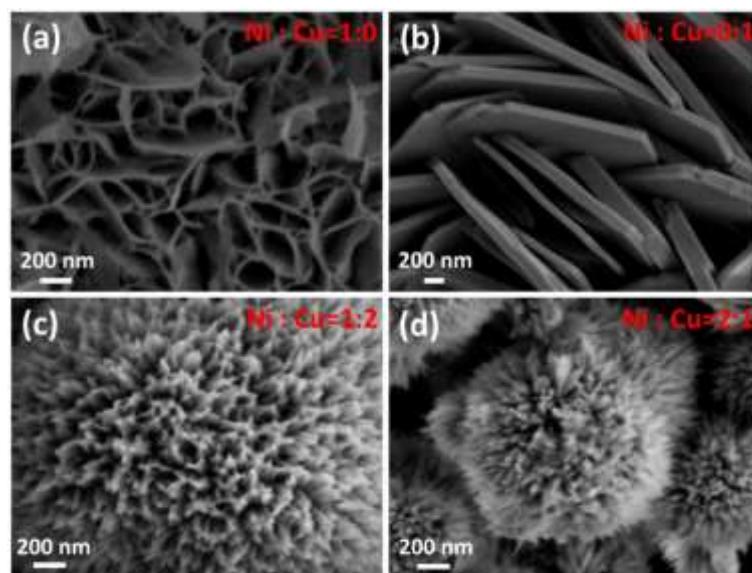


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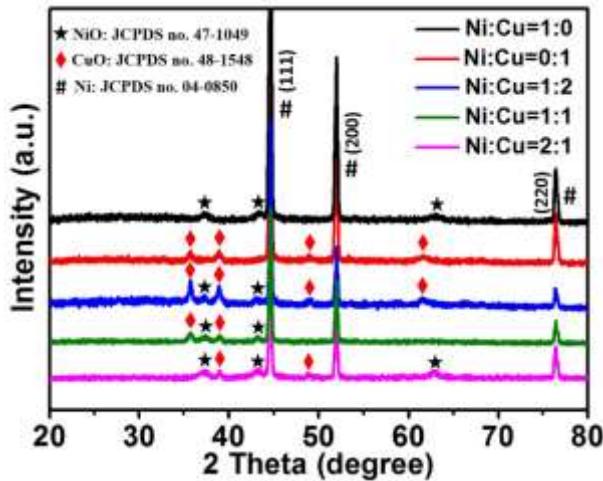


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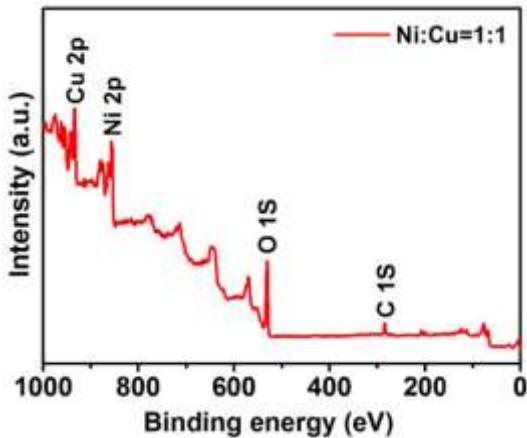


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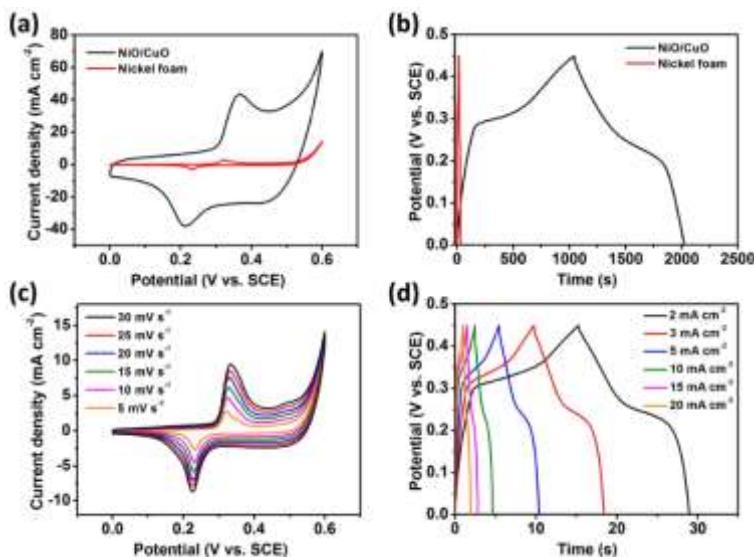


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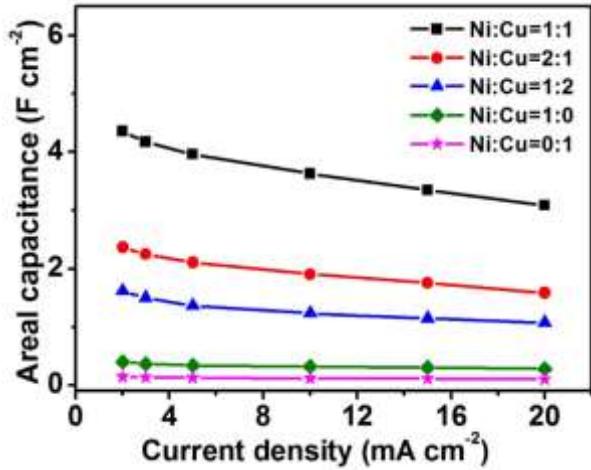


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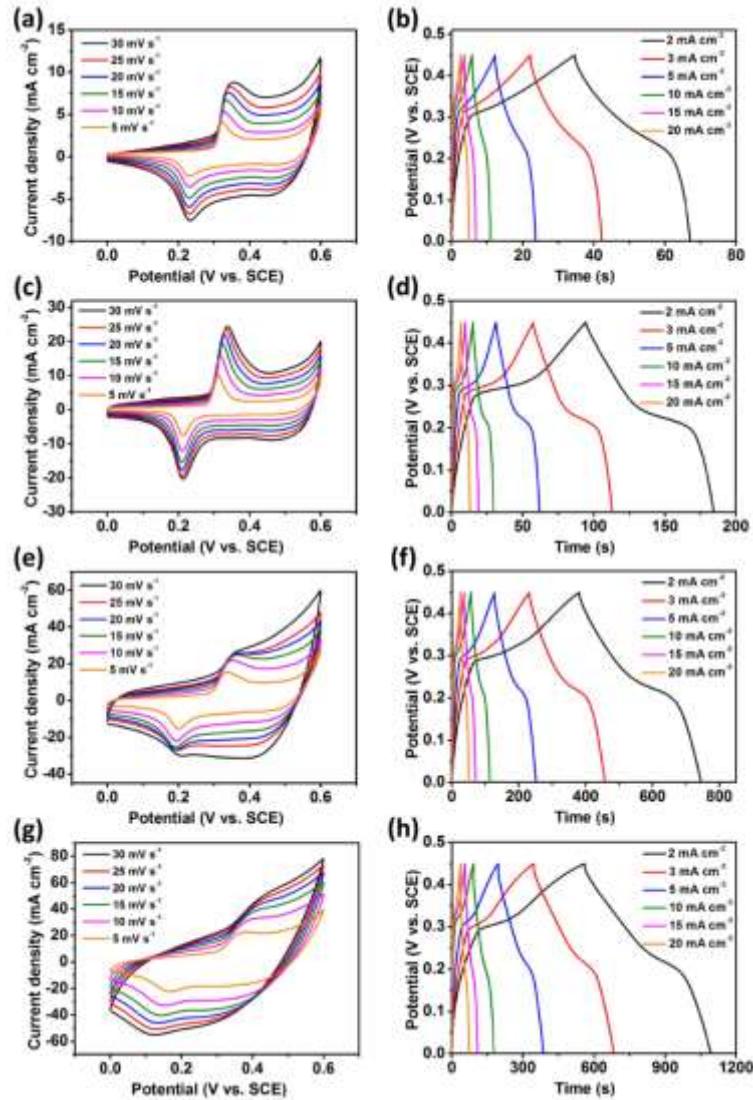


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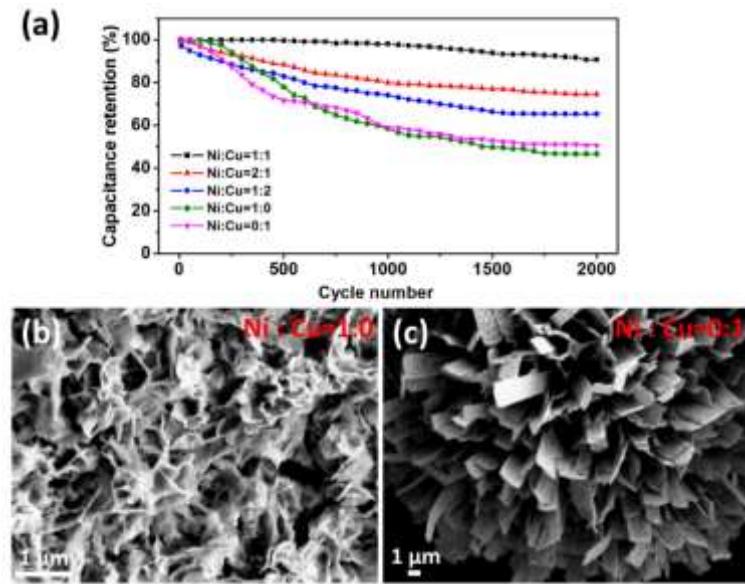


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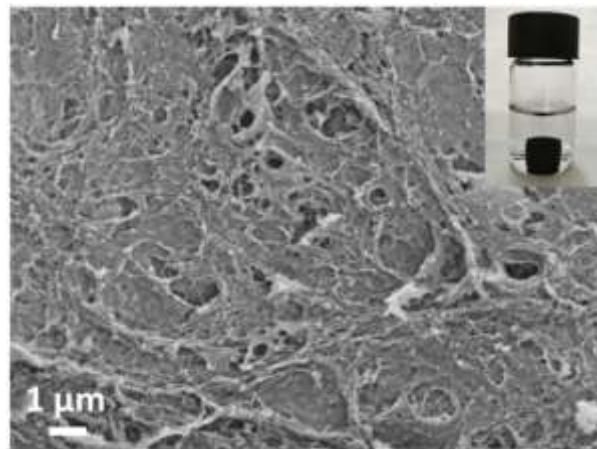


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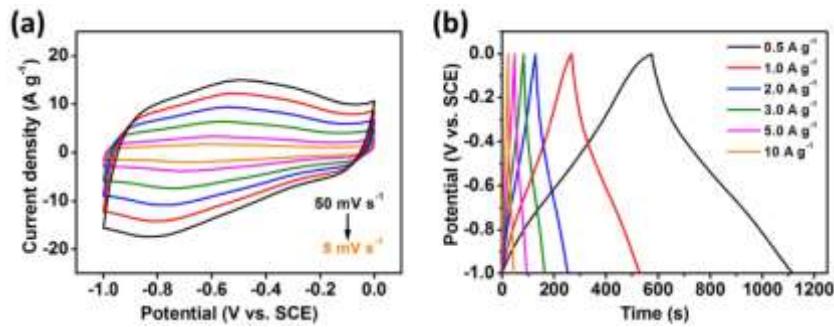


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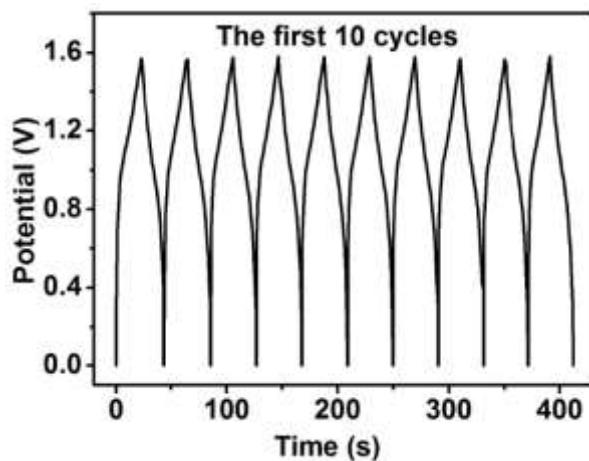


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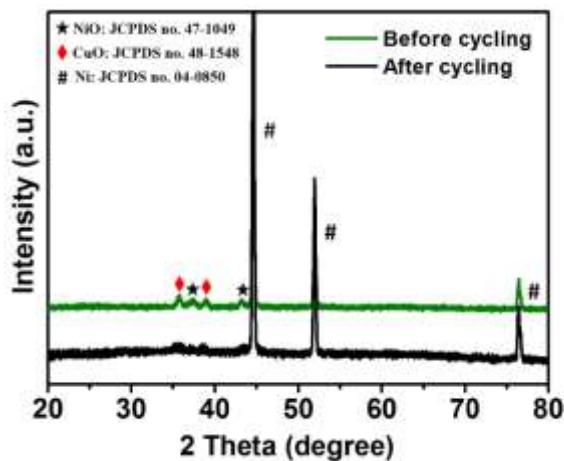


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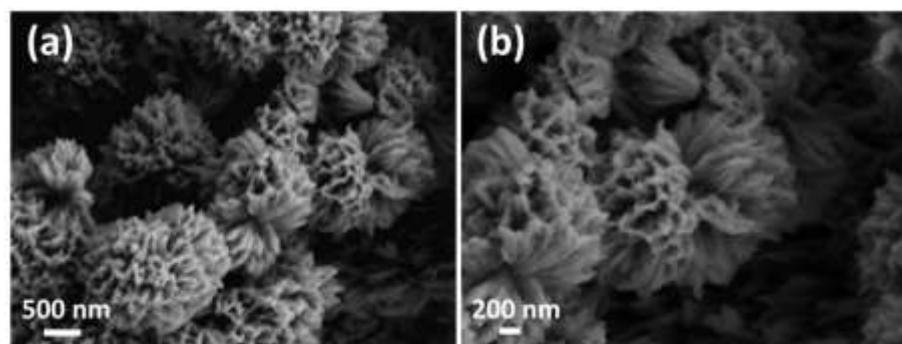


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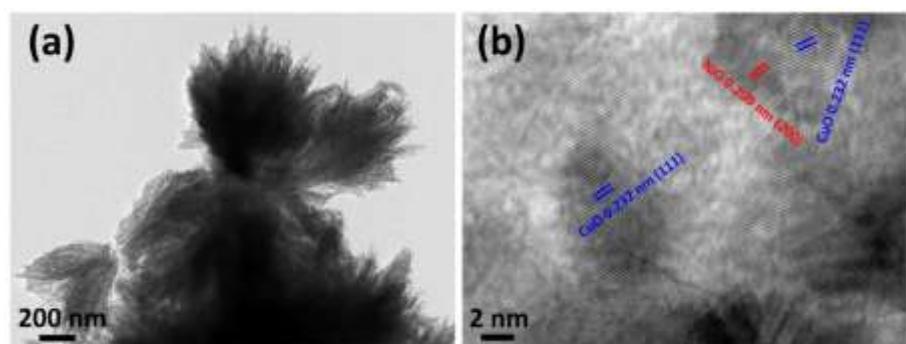


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Materials	Specific capacitance (F g ⁻¹)	Areal capacitance (F cm ⁻²)	Current density or scan rate	Electrolyte	Reference
NiO	302	-	1 A g ⁻¹	6 M KOH	S1
CuO	431	1.51	3.5 mA cm ⁻²	3 M KOH	S2
Cu ₂ O/CuO/Co ₃ O ₄	318	-	0.5 A g ⁻¹	3 M KOH	S3
NiO/NiMn-LDH	937	-	0.5 A g ⁻¹	3 M KOH	S4
CuCo ₂ O ₄ /CuO	781	-	2 mV s ⁻¹	1 M KOH	S5
Ni _{0.99} Cu _{0.01} O	559	-	0.3 A g ⁻¹	6 M KOH	S6
Ni/NiO	526	-	1 A g ⁻¹	3 M KOH	S7
NiO/α-Ni(OH) ₂	707	-	2 A g ⁻¹	2 M KOH	S8
Ni-Co binary hydroxide	1030	-	1 mg cm ⁻²	6 M KOH	S9
NiO@MnO ₂	266.7	-	0.5 A g ⁻¹	2 M KOH	S10
NiO-Co ₃ O ₄	801	-	1 A g ⁻¹	3 M KOH.	S11
ZnO-NiO	649	-	5.8 A g ⁻¹	3 M KOH	S12
Cu/Ni-based manganese dioxide	374	-	0.25 A g ⁻¹	1 M Na ₂ SO ₄	S13
NiCo ₂ O ₄ nanowires	743	-	1 A g ⁻¹	1 M KOH	S14
NiCu(OH) ₂ CO ₃	971	-	1 A g ⁻¹	6 M KOH	S15
NiO-CuO	1450.8	4.35	2 mA cm ⁻²	3 M KOH	Our work

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